# 0.3 mm Pitch, 1.2 mm above the board, Top and bottom Contact, Back-Flip actuator Flexible Printed Circuit ZIF Connectors

FH39 Series

VEV



# •Small size (39 pos. shown)

# Features

1. Low-profile 0.3mm pitch connector with top and bottom contact

Usable via either its top or bottom contact point, this connector achieves enhanced freedom in terms of the product design.

2. High contact reliability thanks to the spring terminal structure

Because both top and bottom contact points are springloaded, the contact point adapts to the FPC motion, and high contact reliability is ensured.

### 3. Delivered with the actuator open

FPC can be immediately inserted without the need for the opening of the actuator.

### 4. Easy FPC insertion

Entry chamfers at all sides of the FPC insertion slot assure correct insertion and positioning of the FPC.

### 5. Accepts standard FPC thickness

0.2mm thick standard Flexible Printed Circuit (FPC) can be used. This is the only ultra-low profile ZIF connector using standard FPC.

# 6. Conductive traces on the PCB can run under the connector

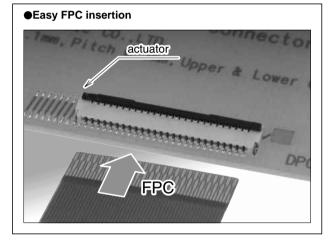
No exposed contacts on the bottom of the connector.

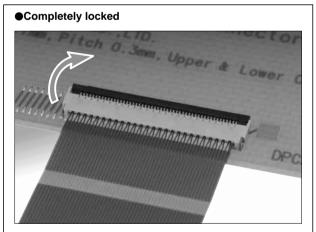
### 7. Board placement with automatic equipment

Flat upper surface and tape and reel packaging facilitate vacuum pick-up and placement. Standard reel packaging contains 5000 connectors.

### 8. Halogen-free\* (FH39J Series)

\*As defined by IEC61249-2-21 Br-900ppm maximum, CI-900ppm maximum, CI + Br combined-1,500ppm maximum





■Specifications							
Ratings	Current rating	0.2 A	Operating temperature range	-55 to +85°C (Note 1)	Storage temperature range	-10 to +50°C (Note 2)	
Ratings	Voltage rating	30 Vrms AC		Relative humidity 90% max. (No condensation)		Relative humidity 90% max. (No condensation)	

Recommended FPC

Thickness:  $0.2 \pm 0.03$  mm, Gold plated contact pads

Item	Specification	Conditions
1.Insulation resistance	50 MΩ min.	100 V DC
2.Withstanding voltage	No flashover or insulation breakdown	90 Vrms AC / 1 minute
3.Contact resistance	100 m $\Omega$ max. * Including FPC and FFC conductor resistance	1 mA, AC max (AC: 1kHz)
4.Durability	Contact resistance: 100 m $\Omega$ max. No damage, cracks, or parts dislocation	10 cycles
5.Vibration	No electrical discontinuity of $1\mu$ s or longer Contact resistance: 100 m $\Omega$ max. No damage, cracks, or parts dislocation	Frequency: 10 to 55 Hz, single amplitude of 0.75 mm, 10 cycles in each of the 3 axis
6.Shock	No electrical discontinuity of $1\mu$ s or longer Contact resistance: 100 m $\Omega$ max. No damage, cracks, or parts dislocation	Acceleration of 981m/s <sup>2</sup> , 6 ms duration, sine half-wave, 3 cycles in each of the 3 axis
7.Humidity (Steady state)	Contact resistance: $100 \text{ m}\Omega$ max. Insulation resistance: $50 \text{ M}\Omega$ min. No damage, cracks, or parts dislocation	96 hours at $40^\circ\!\!C$ and humidity of 90 to 95%
8.Temperature cycle	Contact resistance: $100 \text{ m}\Omega$ max. Insulation resistance: $50 \text{ M}\Omega$ min. No damage, cracks, or parts dislocation	Temperature: $-55^{\circ}C \rightarrow +15^{\circ}C$ to $+35^{\circ}C \rightarrow +85^{\circ}C \rightarrow +15^{\circ}C$ to $+35^{\circ}C$ Time: $30 \rightarrow 2$ to $3 \rightarrow 30 \rightarrow 2$ to 3 minutes 5 cycles
9.Resistance to soldering heat No deformation of components affecting performance		Reflow: At the recommended temperature profile Manual soldering: $350^{\circ}C \pm 5^{\circ}C$ for 5 seconds

Note 1: Includes temperature rise caused by current flow.

Note 2: The term "storage" refers to products stored for a long period prior to mounting and use. The operating temperature and humidity range covers the non-conducting condition of installed connectors in storage, shipment or during transportation after board mounting.

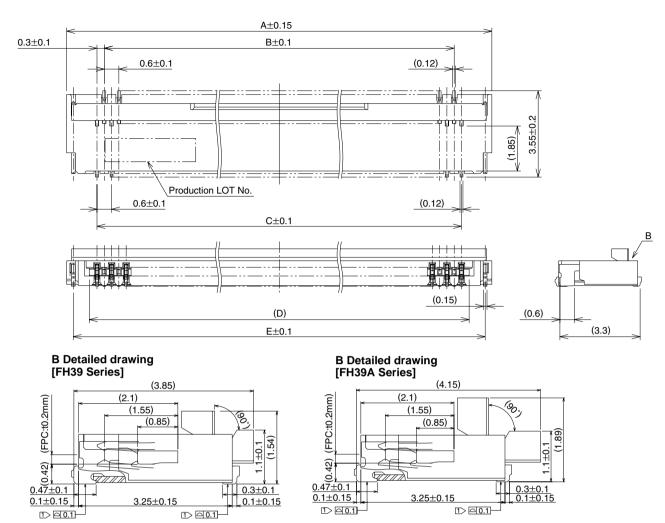
Note 3: Information contained in this catalog represents general requirements for this Series. Contact us for the drawings and specifications for a specific part number shown.

### Materials

Part	Material	Finish	Remarks
Insulator	LCP	Color:Beige	UL94V-0
Insulator	PA	Color:Black	01940-0
Contacts	Dhoonbor bronzo	Gold plated	
Metalfittings	Phosphor bronze	Pure tin reflow plated	

# ■Ordering information

$\frac{FH}{\bullet} \xrightarrow{39} \frac{J}{\bullet} - \frac{51S}{\bullet}$	$- \frac{0.3}{6} \frac{\text{SHW}}{6} \frac{(10)}{6}$				
Series name:FH	Number of positions				
2 Series No.:39	FH39 :25 to 61				
Blank :Standard	FH39A:67, (71 under planning)				
A :Long actuator type	FH39J :25 to 51				
J :Halogen-free requirements	Ontact pitch:0.3mm				
(Flame retardance UL94V-0).	6 Termination type				
	SHWSMT horizontal staggered row mount type				
	Plating specifications				
	(10)Gold plating with nickel barrier				



■Connector Dimensions

Note 1: The coplanarity of each terminal lead within specified dimension is 0.1 mm Max.

2 : Packaged on tape and reel only. Check packaging specification.

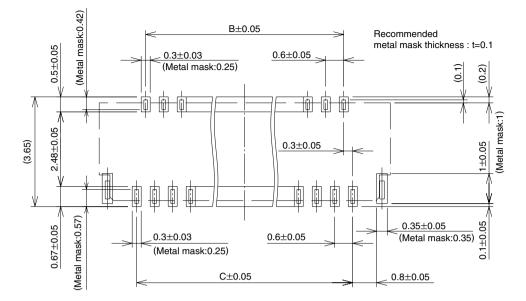
3 : Slight variations in color of the plastic compounds do not affect form, fit or function of the connector.

4 : After reflow, the terminal plating may change color, however this does not represent a quality issue.

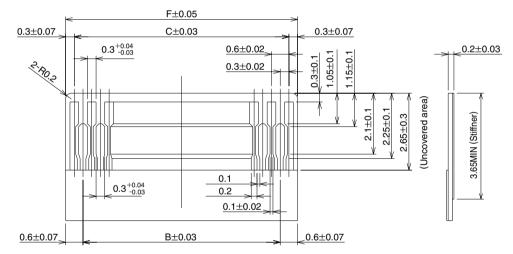
					A	All dimens	ions: mm
Part Number	CL No.	Number of contacts	А	В	С	D	E
FH39-25S-0.3SHW(10)	580-1806-8-10	25	9.7	6.6	7.2	7.83	9.15
FH39-27S-0.3SHW(10)	580-1805-5-10	27	10.3	7.2	7.8	8.43	9.75
FH39-29S-0.3SHW(10)	580-1807-0-10	29	10.9	7.8	8.4	9.03	10.35
FH39-33S-0.3SHW(10)	580-1803-0-10	33	12.1	9	9.6	10.23	11.55
FH39-39S-0.3SHW(10)	580-1800-1-10	39	13.9	10.8	11.4	12.03	13.35
FH39-45S-0.3SHW(10)	580-1802-7-10	45	15.7	12.6	13.2	13.83	15.15
FH39-51S-0.3SHW(10)	580-1801-4-10	51	17.5	14.4	15	15.63	16.95
FH39-61S-0.3SHW(10)	580-1808-3-10	61	20.5	17.4	18	18.63	19.95
FH39A-67S-0.3SHW(10)	580-1809-6-10	67	22.3	19.2	19.8	20.43	21.75
FH39A-71S-0.3SHW(10)	Under planning	71	23.5	20.4	21	21.63	22.95
FH39J-25S-0.3SHW(10)	580-1815-9-10	25	9.7	6.6	7.2	7.83	9.15
FH39J-33S-0.3SHW(10)	580-1814-6-10	33	12.1	9	9.6	10.23	11.55
FH39J-39S-0.3SHW(10)	580-1813-3-10	39	13.9	10.8	11.4	12.03	13.35
FH39J-45S-0.3SHW(10)	580-1811-8-10	45	15.7	12.6	13.2	13.83	15.15
FH39J-51S-0.3SHW(10)	580-1812-0-10	51	17.5	14.4	15	15.63	16.95

Tape and reel packaging (5,000 pieces/reel). Order by number of reels.

# ■Recommended PCB mounting pattern and metal mask dimensions



## Recommended FPC Dimensions

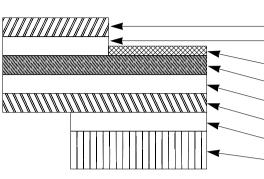


\* Stiffener dimension should be 3.65mm min., and X dimension should be 0.5mm for improved flexibility of FPC.

				All o	dimensions: mm
Part Number	CL No.	Number of contacts	В	С	F
FH39-25S-0.3SHW(10)	580-1806-8-10	25	6.6	7.2	7.8
FH39-27S-0.3SHW(10)	580-1805-5-10	27	7.2	7.8	8.4
FH39-29S-0.3SHW(10)	580-1807-0-10	29	7.8	8.4	9
FH39-33S-0.3SHW(10)	580-1803-0-10	33	9	9.6	10.2
FH39-39S-0.3SHW(10)	580-1800-1-10	39	10.8	11.4	12
FH39-45S-0.3SHW(10)	580-1802-7-10	45	12.6	13.2	13.8
FH39-51S-0.3SHW(10)	580-1801-4-10	51	14.4	15	15.6
FH39-61S-0.3SHW(10)	580-1808-3-10	61	17.4	18	18.6
FH39A-67S-0.3SHW(10)	580-1809-6-10	67	19.2	19.8	20.4
FH39A-71S-0.3SHW(10)	Under planning	71	20.4	21	21.6
FH39J-25S-0.3SHW(10)	580-1815-9-10	25	6.6	7.2	7.8
FH39J-33S-0.3SHW(10)	580-1814-6-10	33	9	9.6	10.2
FH39J-39S-0.3SHW(10)	580-1813-3-10	39	10.8	11.4	12
FH39J-45S-0.3SHW(10)	580-1811-8-10	45	12.6	13.2	13.8
FH39J-51S-0.3SHW(10)	580-1812-0-10	51	14.4	15	15.6

# ■Recommended FPC construction

# 1. Using Single-sided FPC



Material Name	Material	Material Thickness (µm)
Covering film layer	Polyimide 1 mil thick.	(25)
Cover adhesive		(25)
 Surface treatment	$0.2\mu m$ thick gold plated over 1 to $5\mu m$ nickel underplating	3
 Copper foil	per foil Cu 1oz	
 Base adhesive	Thermosetting adhesive	25
 Base film	Polyimide 1 mil thick	25
 Reinforcement material adhesive	Thermosetting adhesive	40
 Stiffener	Polyimide 3 mil thick	75
	Total	203

# 2. Using Double-sided FPC

# **FPC : Flexible Printed Circuit**

	Material Name	Material	Material Thickness (µm)
	Covering film layer	Polyimide 1 mil thick.	(25)
	Cover adhesive		(25)
→ → → → → → → → → → → → → → → → → → →	Surface treatment	$0.2\mu m$ thick gold plated over 1 to $5\mu m$ nickel underplating	3
<pre>(////////////////////////////////////</pre>	Through-hole copper	Cu	15
<	Copper foil	Cu 1/2oz	18
	Base adhesive	Thermosetting adhesive	18
	Base film	Polyimide 1 mil thick	25
	Base adhesive	Thermosetting adhesive	18
	Copper foil	Cu 1/2oz	(18)
	Cover adhesive	Thermosetting adhesive	25
	Covering film layer	Polyimide 1 mil thick.	25
	Reinforcement material adhesive	Thermosetting adhesive	25
	Stiffener	Polyimide 3 mil thick	25
		Total	197

\* To prevent release of the FPC due to its bending, use of the double sided FPC with copper foil on the back side is NOT RECOMMENDED.

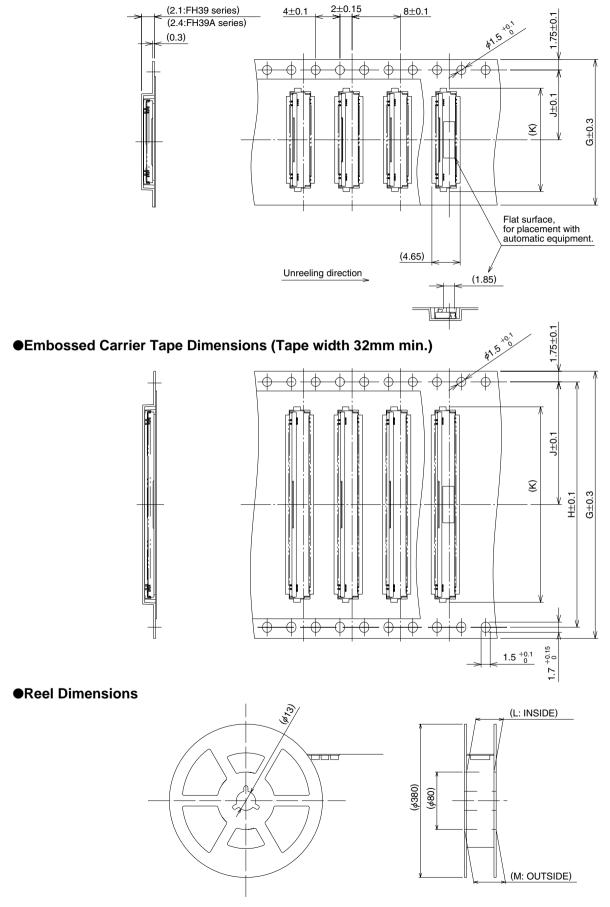
# 3. Precautions

1: This specification is a recommendation for the construction of the FH39 Series FPC (t= $0.2\pm0.05$ ).

2: For details about the construction, please contact the FPC manufacturers.

# ■Packaging Specification

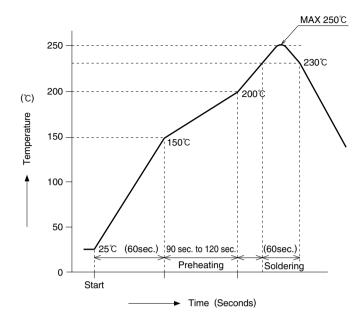
### •Embossed Carrier Tape Dimensions (Tape width to 24mm max.)



						A	All dimens	ions: mm
Part Number	CL No.	Number of contacts	G	Н	J	K	L	М
FH39-25S-0.3SHW(10)	580-1806-8-10	25	24	—	11.5	11	25.4	29.4
FH39-27S-0.3SHW(10)	580-1805-5-10	27	24	_	11.5	11.6	25.4	29.4
FH39-29S-0.3SHW(10)	580-1807-0-10	29	24	—	11.5	12.2	25.4	29.4
FH39-33S-0.3SHW(10)	580-1803-0-10	33	24	_	11.5	13.4	25.4	29.4
FH39-39S-0.3SHW(10)	580-1800-1-10	39	24	_	11.5	15.2	25.4	29.4
FH39-45S-0.3SHW(10)	580-1802-7-10	45	32	28.4	14.2	17	33.4	37.4
FH39-51S-0.3SHW(10)	580-1801-4-10	51	32	28.4	14.2	18.8	33.4	37.4
FH39-61S-0.3SHW(10)	580-1808-3-10	61	44	40.4	20.2	21.8	45.4	49.4
FH39A-67S-0.3SHW(10)	580-1809-6-10	67	44	40.4	20.2	23.6	45.4	49.4
FH39A-71S-0.3SHW(10)	Under planning	71	44	40.4	20.2	24.8	45.4	49.4
FH39J-25S-0.3SHW(10)	580-1815-9-10	25	24	_	11.5	11	25.4	29.4
FH39J-33S-0.3SHW(10)	580-1814-6-10	33	24	_	11.5	13.4	25.4	29.4
FH39J-39S-0.3SHW(10)	580-1813-3-10	39	24	_	11.5	15.2	25.4	29.4
FH39J-45S-0.3SHW(10)	580-1811-8-10	45	32	28.4	14.2	17	33.4	37.4
FH39J-51S-0.3SHW(10)	580-1812-0-10	51	32	28.4	14.2	18.8	33.4	37.4

Tape and reel packaging (5,000 pieces/reel).

# ■Temperature Profile



### **HRS test condition**

Solder method	:Reflow, IR/hot air
Environment	:Room air
Solder composition	:Paste, 96.5%Sn/3.0%Ag/0.5%Cu
	(Senju Metal Industry, Co., Ltd.'s
	Part Number:M705-221CM5-32-10.5)
Test board	:Glass epoxy 25mm×50mm×0.8mm thick
Land dimensions	:0.3mm×0.5mm, 0.3mm×0.67mm
Metal mask	:0.25×0.42, 0.25×0.57×0.1mm thick

The temperature profiles shown are based on the above conditions.

In individual applications the actual temperature may vary, depending on solder paste type, volume / thickness and board size / thickness. Consult your solder paste and equipment manufacturer for specific recommendations.

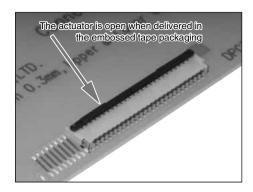
# **Connector Operation and Precautions**

### Operation

Exercise care when handling connectors. Follow recommendations given below.

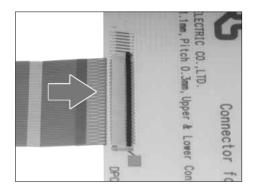
### 1. As delivered

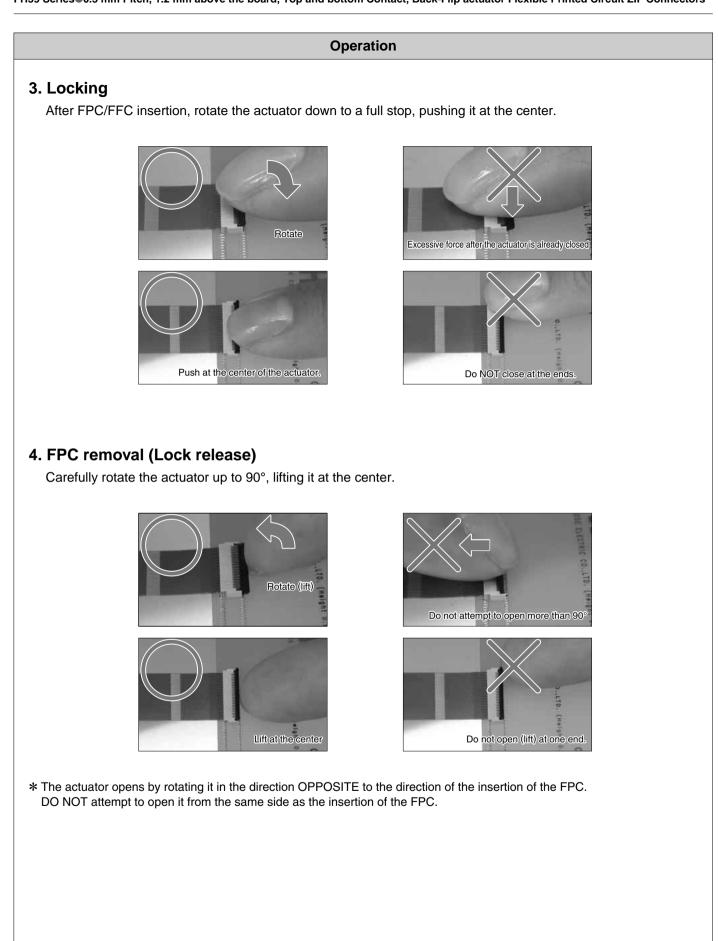
Delivered with the actuator open. There is no need to operate the actuator prior to the insertion of the FPC.



### 2. FPC insertion

Align the FPC perpendicular with the connector and insert it firmly all the way.





### Precautions when mounting connectors on the PCB

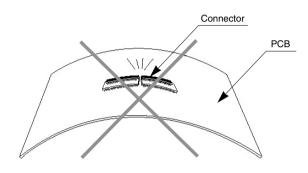
### Handling before mounting on PCB

Insertion of the FPC or operation of the actuator prior to mounting on the PCB is NOT RECOMMENDED.

♦PC board warpage

Minimize the warpage as much as possible. The connector is straight within 0.1 mm max. Make sure that the mounting area flatness can accept the connector terminals without causing any failure of the solder joints.

- ♦Forces on the board
- When braking the large PC board into individual boards exercise care NOT to damage the installed connectors.
- ♦When attaching the boards or other components with the screws make sure that any stresses will NOT cause board deflections affecting the mounting areas of the connector.



### **Other precautions**

### ♦When hand soldering:

Do not perform hand soldering with the FPC inserted in the connector.

- Do not apply excessive heat or touch the soldering iron anywhere other than the connector leads.
- Do not use excessive amount of solder or flux compounds.

Operation of the actuator or contacts may be affected by excessive amounts of solder or flux compounds.